MICROCHIP

Semiconductor Device Type: HZA 008 UDFN 2x2x0.6mm MatteTin

Termination Base Alloy: Copper Alloy (Cu)

Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm
Silica, fused	60676-86-0	Mold Compound	26.262	1.549	262,620
Epoxy Resin	Trade Secret	Mold Compound	1.415	0.083	14,152
Phenolic Resin	Trade Secret	Mold Compound	1.415	0.083	14,152
Carbon Black	1333-86-4	Mold Compound	0.088	0.005	875
Copper	7440-50-8	Lead Frame	60.810	3.588	608,096
Iron	7439-89-6	Lead Frame	1.496	0.088	14,958
Silver	7440-22-4	Lead Frame	1.213	0.072	12,125
Zinc	7440-66-6	Lead Frame	0.080	0.005	796
Phosphorous	7723-14-0	Lead Frame	0.053	0.003	525
Silver	7440-22-4	Die Attach	0.801	0.047	8,008
Epoxy resin	68475-94-5	Die Attach	0.208	0.012	2,080
Copper(II) oxide	1317-38-0	Die Attach	0.031	0.002	312
Silicon	7440-21-3	Chip (Die)	4.810	0.284	48,100
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	0.099	0.006	985
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.002	0.000	15
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.220	0.072	12,200
		TOTALS:	**100.000**	**5.900**	**1,000,000**

0.0059 g Total Mass

Package Homogeneous Materials

J-STD-609A Product Marking and/or Pkg. Labeling e3

1.72	**(mg) Total**	**Mold Compound**	**% ot Total Weight**	**29.18**
	Silica, fused	60676-86-0	90.0000	
	Epoxy Resin	Trade Secret	4.85000	
	Phenolic Resin	Trade Secret	4.85000	
	Carbon Black	1333-86-4	0.30000	
		Total	**100.00**	
3.76	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**63.65**
	Copper	7440-50-8	95.54	
	Iron	7439-89-6	2.35	
	Silver	7440-22-4	1.91	
	Zinc	7440-66-6	0.13	
	Phosphorous	7723-14-0	0.08	
		Total	**100.00**	
0.06	**(mg) Total**	**Die Attach**	**% of Total Weight**	**1.04**
	Silver	7440-22-4	77.00	
	Epoxy resin	68475-94-5	20.00	
	Copper(II) oxide	1317-38-0	3.00	
		Total	**100.00**	
0.28	**Total (mg)**	**Chip (Die)**	**% of Total Weight**	**4.81**
	Doped Silicon	7440-21-3	100.00	
		Total	**100.00**	
0.01	**(mg) Total**	**Wire Bond Copper palladium coated (CuPd)**	**% of Total Weight**	**0.10**
	Copper	7440-50-8	98.50	
	Palladium	7440-05-3	1.50	
		Total	**100.00**	
0.07	**(mg) Total**	**Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour**	**% of Total Weight**	**1.22**
	Tin	7440-31-5	100.00	
		Total	**100.00**	
5.900				**100.00**

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table